

Search Notes

Application/Control No.

10/687,085

Examiner

Stephen W. Smoot

Applicant(s)/Patent under
Reexamination

MAEDA, HIROSHI

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
438	108	1/12/2005	SWS
438	118	1/12/2005	SWS
438	126	1/12/2005	SWS
438	127	1/12/2005	SWS
438	132	1/12/2005	SWS
438	601	1/12/2005	SWS
438	612	1/12/2005	SWS
438	613	1/12/2005	SWS
438	958	1/12/2005	SWS
Updated	Above	5/23/2005	SWS

INTERFERENCE SEARCHED

Class	Subclass	Date	Examiner
Same as Above		5/23/2005	SWS

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Key Words: Chip, Die, IC - Pad; Solder - Bump, Ball; Polyimide; Passivation; Fuse;	1/12/2005	SWS
Chip Carrier, Package Substrate, Wiring Substrate; Flip Chip Assembly; Underfilled.	1/12/2005	SWS
Updated Above Search	5/23/2005	SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	1/12/2005 5-23-05	SWS SWS